

**P-Channel MOSFET** 

## **General Description**

The WSM150P06G is the highest performance SGT P-Channel MOSFET with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The WSM150P06G meet the RoHS and Green Product requirement, 100%  $E_{AS}$  guaranteed with full function reliability approved.

#### **Features**

- 100% UIS + R<sub>g</sub> Tested.
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

## **Product Summery**

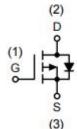
BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	l <sub>D</sub>
-60V	3.2mΩ	-150A

## **Applications**

- Power Management for Industrial DC/DC Converters
- Load switch
- Battery protection

### **TOLL-8L Pin Configuration**





# **Absolute Maximum Ratings** (T<sub>A</sub>=25°C, Unless Otherwise Noted)

Symbol	Parameter		Rating	Units	
$V_{DS}$	Drain-Source Voltage		-60	V	
V <sub>GS</sub>	Gate-Source Voltage		±20	V	
ı 7	Continuous Drain Current	T <sub>C</sub> =25°C	-150		
I <sub>D</sub> <sup>7</sup>	Continuous Drain Current	T <sub>C</sub> =100°C	-100	Α	
I <sub>DM</sub> <sup>3</sup>	Pulse Drain Current		-650		
P <sub>D</sub> <sup>2</sup>	Power Dissipation	T <sub>C</sub> =25°C	185	W	
I <sub>AS</sub> <sup>3</sup>	Single pulse Avalanche Current		-90	Α	
E <sub>AS</sub> <sup>3</sup>	Single pulse Avalanche Energy	L=0.3mH	2025	mJ	
T <sub>STG</sub>	Storage Temperature Range		-55 to 150	- °C	
TJ	Operating Junction Temperature Range		-55 to 150		
D 1.4	Thermal Pagistance Junction to Ambient	t≤10s	20		
R <sub>θJA</sub> <sup>1,4</sup>	Thermal Resistance-Junction to Ambient	Steady State	60	°C/W	
$R_{ heta JC}$	Thermal Resistance-Junction to Case		0.68		



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### Electrical Characteristics (T<sub>J</sub>=25°C, Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250μA	-60			V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V , I <sub>D</sub> =-20A		3.2	4.2	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_{D}=-250\mu A$	-2.0	-2.4	-3.0	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-60V , V <sub>GS</sub> =0V			-1.0	μA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{DS}$ =0V , $V_{GS}$ =±20V			±100	nA
9 <sub>fs</sub>	Forward Transconductance	$V_{DS}$ =-5V , $I_{D}$ =-20A		50		S
$R_G$	Gate Resistance	f=1.0MHz		2.5		Ω
$Q_g$	Total Gate Charge (10V)			135		
$Q_{gs}$	Gate-Source Charge	$V_{DS}$ =-30V , $V_{GS}$ =-10V , $I_{D}$ =-20A		29		nC
$Q_{gd}$	Gate-Drain Charge			23		
T <sub>d(on)</sub>	Turn-On Delay Time			70		
T <sub>r</sub>	Rise Time	$V_{DS}$ =-30V , $V_{GS}$ =-10V , $I_{D}$ =-20A		45		no
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_L=1\Omega$ , $R_{GEN}=3\Omega$		168		ns
T <sub>f</sub>	Fall Time	- L , GLN		50		
C <sub>iss</sub>	Input Capacitance			9200		
C <sub>oss</sub>	Output Capacitance	$V_{DS}$ =-30V , $V_{GS}$ =0V , $f$ =1.0MHz		1600		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			89		

#### **Diode Characteristics**

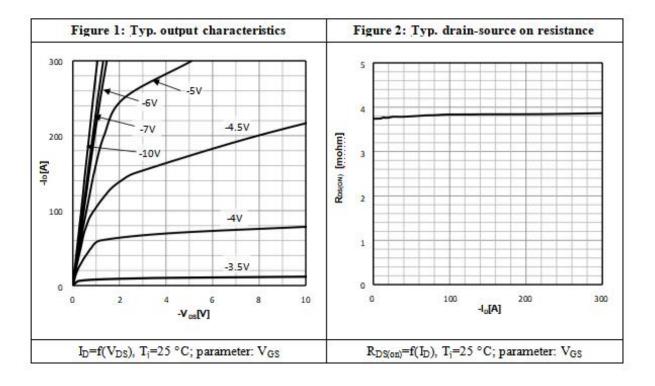
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
I <sub>S</sub> <sup>7</sup>	Continuous Source Current				-150	Α
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A		-0.7	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	L = 20A di/dt=E00A/wa		46		ns
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =-20A , di/dt=500A/μs		102		nC

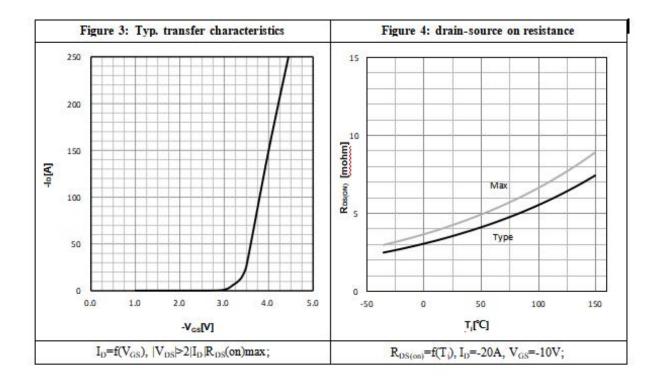
#### Note:

- The value of R<sub>θJA</sub> is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The Power dissipation P<sub>DSM</sub> is based on R<sub>θJA</sub> t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 2. The power dissipation  $P_D$  is based on  $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- 3. Single pulse width limited by junction temperature  $T_{J(MAX)}$ =150°C.
- 4. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to case  $R_{\theta JC}$  and case to ambient.
- 5. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.
- 6. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T<sub>J(MAX)</sub>=150°C. The SOA curve provides a single pulse rating.
- 7. The maximum current rating is package limited.
- 8. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C.
- 9. The maximum current rating is silicon limited



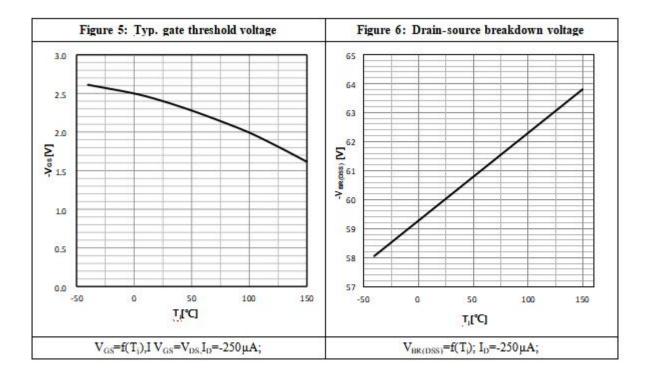
# **Typical Characteristics**

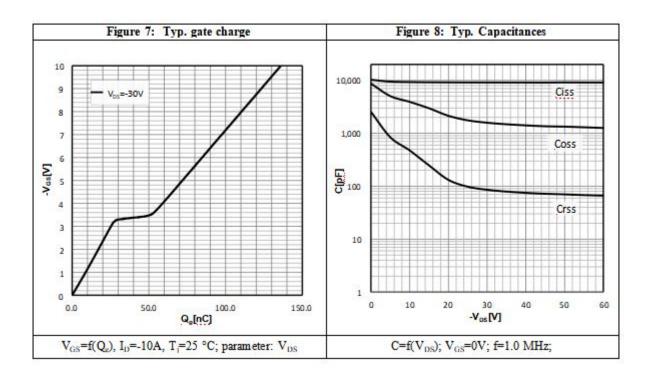






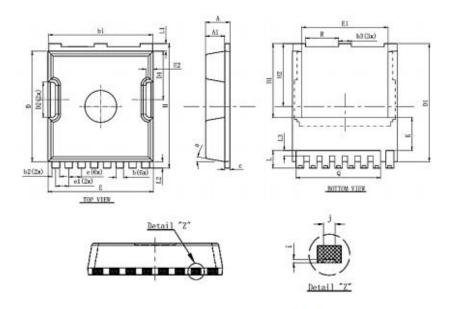
# **Typical Characteristics (Cont.)**







# **Packaging information**



Symbol		Dimensions In Millimeters		
Symbol	Min.	Nom	Max.	
A	2.2	2.3	2.4	
A1	1.7	1.8	1.9	
b	0.6	0.7	0.8	
b1	9.7	9.8	9.9	
b2	0.65	0.75	0.85	
b3	1.1	1.2	1.3	
С	0.4	0.5	0.6	
D	10.3	10.4	10.5	
D1	11.0	11.1	11.2	
D2	3.2	3.3	3.4	
D4	4.47	4.57	4.67	
E	9.8	9.9	10.0	
E1	8.0	8.1	8.2	
E2	0.5	0.6	0.7	
е	1.200 (BSC)			
e1	1.225 (BSC)			
Н	11.6	11.7	11.8	
H1	6.95BSC			
H2		5.9BSC		
1		0.1REF		
j		0.350REF		
K		3.100REF		
L	1.55	1.65	1.75	
L1	0.6	0.7	0.8	
L2	0.5	0.6	0.7	
L3	0.4	0.5	0.6	
Q		7.95REF		
R	3.0	3.1	3.2	
θ	10°REG			



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